

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00169	1.06	0.02544
	Doped silicon	Silicon (Si)	7440-21-3	0.15796	98.94	2.37456
Subtotal				0.15965	100	2.4
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01143	10.0	0.17187
	Silver alloy	Silver (Ag)	7440-22-4	0.00229	2.0	0.03437
	Lead alloy	Lead (Pb)	7439-92-1	0.10061	88.0	1.51248
Subtotal				0.11433	100	1.71872
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.28566	100.0	4.29417
Subtotal				0.28566	100	4.29417
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.00929	0.03	0.13965
	Copper alloy	Iron (Fe)	7439-89-6	0.03406	0.11	0.51205
	Copper alloy	Copper (Cu)	7440-50-8	30.92262	99.86	464.8483
Subtotal				30.96597	100	465.5
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.32263	100.0	4.85
Subtotal				0.32263	100	4.85
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	5.45214	8.0	81.96
	Filler	Silica fused	60676-86-0	55.20292	81.0	829.845
	Metal hydroxide	Metal hydroxide		0.47706	0.7	7.1715
	Carbon Black	Carbon black	1333-86-4	0.20446	0.3	3.0735
	Polymer	Epoxy resin system		6.81518	10.0	102.45
Subtotal				68.15176	100	1024.5
Total				100	100	1503.26289

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